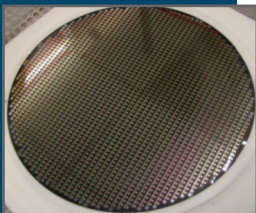
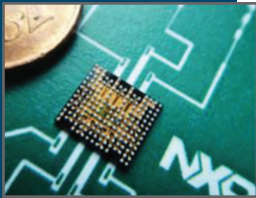
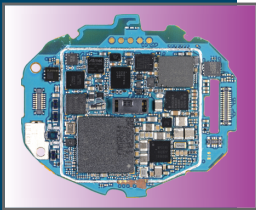


# Advanced Packaging Update: Market and Technology Trends

Vol. 3-0716



The Advanced Packaging Update (3-0716) features an explanation of the drivers for fan-out wafer level packages (FO-WLPs) in high volume manufacturing and analysis of economic and technical issues that need to be addressed in large area panel production. Special coverage of trends in packaging and assembly for wearable electronics is provided. Recent developments in battery technology are included. An economic analysis examines macroeconomic trends and their impact on the semiconductor packaging and assembly industry.

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